

ATTORNEY DOCKET NO.: CSAY-0020



#61a  
Hawkins  
5/1/02  
COPY OF PAPERS  
ORIGINALLY FILED  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: James E. Flowers

Serial No.: 09/755,991

Filed: January 5, 2001

Title: MODULE HAVING DUAL-BAND SURFACE ACOUSTIC WAVE  
CIRCUITS AND METHOD OF MANUFACTURING THE SAME

Grp./A.U.: 2834

Examiner: P. Cuevas

RECEIVED  
APR 23 2002  
TECHNICAL CENTER 2800

Honorable Commissioner of Patents  
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service  
as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C.  
20231, on 03/28/2002 (Date)  
Sean A. Smith  
(Printed or typed name of person signing the certificate)  
Sean A. Smith  
(Signature of the person signing the certificate)

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.111

In response to the Examiner's Action mailed March 12, 2002, please amend the above-  
identified application as follows:

✓ IN THE SPECIFICATION:

Please rewrite the title as follows:

HERMETICALLY SEALED DUAL-BAND SURFACE ACOUSTIC WAVE CIRCUIT  
MODULE